CY74FCT163245
CY74FCT163H245

16-Bit Transceivers

SCCS051 - February 1997 - Revised March 2000

Features

- **Low power, pin-compatible replacement for LCX and LPT families**
- **5V tolerant inputs and outputs**
- **24 mA balanced drive outputs**
- **Power-off disable outputs permits live insertion**
- **Edge-rate control circuitry for reduced noise**
- **FCT-C speed at 4.1 ns**
- **Latch-up performance exceeds JEDEC standard no. 17**
- **Typical output skew < 250ps**
- **Industrial temperature range of –40˚C to +85˚C**
- **TSSOP (19.6-mil pitch) or SSOP (25-mil pitch)**
- **Typical V_{olp} (ground bounce) performance exceeds Mil Std 883D**
- **V_{CC} = 2.7V to 3.6V**
- **ESD (HBM) > 2000V**

CY74FCT163H245

- **Bus hold on data inputs**
- **Eliminates the need for external pull-up or pull-down resistors**
- **Devices with bus hold are not recommended for translating rail-to-rail CMOS signals to 3.3V logic levels**

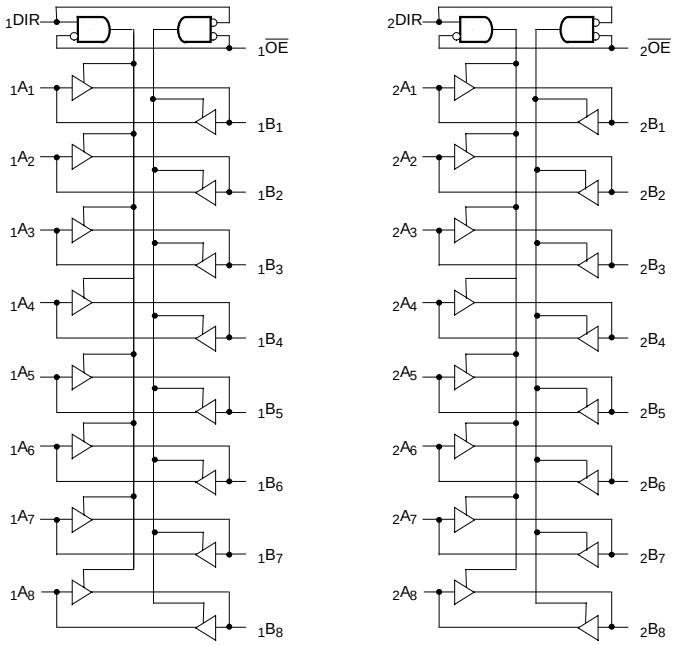
Functional Description

These 16-bit transceivers are designed for use in bidirectional synchronous communication between two buses, where high speed and low power are required. Direction of data flow is controlled by (DIR), the Output Enable ($\overline{OE}$) transfers data when LOW and isolates the buses when HIGH. The outputs are 24-mA balanced output drivers with current limiting resistors to reduce the need for external terminating resistors and provide for minimal undershoot and reduced ground bounce..

The CY74FCT163H245 has “bus hold” on the data inputs, which retains the input’s last state whenever the input goes to high impedance. This eliminates the need for pull-up/down resistors and prevents floating inputs.

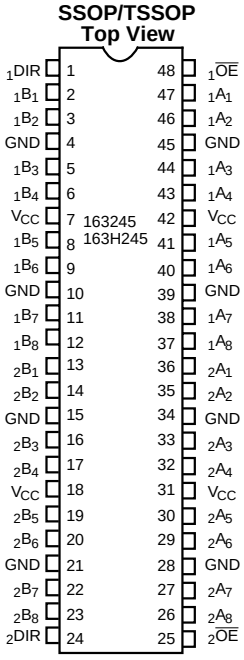
The CY74FCT163245 is designed with inputs and outputs capable of being driven by 5.0V buses, allowing its use in mixed voltage systems as a translator. The outputs are also designed with a power off disable feature enabling its use in applications requiring live insertion.

Logic Block Diagrams CY74FCT163245, CY74FCT163H245



Pin Configuration

SSOP/TSSOP Top View



Pin Description

Name	Description
$\overline{OE}$	Three-State Output Enable Inputs (Active LOW)
DIR	Direction Control
A	Inputs or Three-State Outputs[1]
B	Inputs or Three-State Outputs[1]

Function Table[2]

Inputs		Outputs
$\overline{OE}$	DIR	
L	L	Bus B Data to Bus A
L	H	Bus A Data to Bus B
H	X	High Z State

Maximum Ratings[3, 4]

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature ..... –55°C to +125°C

Ambient Temperature with Power Applied..... –55°C to +125°C

Supply Voltage Range .....0.5V to 4.6V

DC Input Voltage ..... –0.5V to +7.0V

DC Output Voltage..... –0.5V to +7.0V

DC Output Current (Maximum Sink Current/Pin) .....–60 to +120 mA

Power Dissipation 1.0W

Operating Range

Range	Ambient Temperature	V_{CC}
Industrial	–40°C to +85°C	2.7V to 3.6V

Electrical Characteristics for Non Bus Hold Devices Over the Operating Range V_{CC}=2.7V to 3.6V

Parameter	Description	Test Conditions		Min.	Typ.[5]	Max.	Unit
V_{IH}	Input HIGH Voltage	All Inputs		2.0		5.5	V
V_{IL}	Input LOW Voltage					0.8	V
V_H	Input Hysteresis[6]				100		mV
V_{IK}	Input Clamp Diode Voltage	V_{CC}=Min., I_{IN}=–18 mA			–0.7	–1.2	V
I_{IH}	Input HIGH Current	V_{CC}=Max., V_I=5.5				±1	µA
I_{IL}	Input LOW Current	V_{CC}=Max., V_I=GND				±1	µA
I_{OZH}	High Impedance Output Current (Three-State Output pins)	V_{CC}=Max., V_{OUT}=5.5V				±1	µA
I_{OZL}	High Impedance Output Current (Three-State Output pins)	V_{CC}=Max., V_{OUT}=GND				±1	µA
I_{OS}	Short Circuit Current[7]	V_{CC}=Max., V_{OUT}=GND		–60	–135	–240	mA
I_{OFF}	Power-Off Disable	V_{CC}=0V, V_{OUT}≤4.5V				±100	µA
I_{CC}	Quiescent Power Supply Current	V_{IN}≤0.2V, V_{IN}≥V_{CC}–0.2V	V_{CC}=Max.		0.1	10	µA
ΔI_{CC}	Quiescent Power Supply Current (TTL inputs HIGH)	V_{IN}=V_{CC}–0.6V[8]	V_{CC}=Max.		2.0	30	µA

Note:

1. On the CY74FCT163H245, these pins have bus hold.
2. H = HIGH Voltage Level. L = LOW Voltage Level. X = Don't Care. Z = High Impedance.
3. Operation beyond the limits set forth may impair the useful life of the device. Unless otherwise noted, these limits are over the operating free-air temperature range.
4. Unused inputs must always be connected to an appropriate logic voltage level, preferably either V_{CC} or ground.
5. Typical values are at V_{CC}=3.3V, T_A = +25°C ambient.
6. This parameter is specified but not tested.
7. Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.
8. Per TTL driven input; all other inputs at V_{CC} or GND.

Electrical Characteristics For Bus Hold Devices Over the Operating Range V_{CC}=2.7V to 3.6V

Parameter	Description	Test Conditions		Min.	Typ.[5]	Max.	Unit
V_{IH}	Input HIGH Voltage	All Inputs		2.0		V_{CC}	V
V_{IL}	Input LOW Voltage					0.8	V
V_H	Input Hysteresis[6]				100		mV
V_{IK}	Input Clamp Diode Voltage	V_{CC}=Min., I_{IN}=–18 mA			–0.7	–1.2	V
I_{IH}	Input HIGH Current	V_{CC}=Max., V_I=V_{CC}				±100	µA
I_{IL}	Input LOW Current					±100	µA
I_{BBH} I_{BBL}	Bus Hold Sustain Current on Bus Hold Input[9]	V_{CC}=Min.	V_I=2.0V	–50			µA
			V_I=0.8V	+50			µA
I_{BHHO} I_{BHLO}	Bus Hold Overdrive Current on Bus Hold Input[9]	V_{CC}=Max., V_I=1.5V				±500	µA
I_{OZH}	High Impedance Output Current (Three-State Output pins)	V_{CC}=Max., V_{OUT}=V_{CC}				±1	µA
I_{OZL}	High Impedance Output Current (Three-State Output pins)	V_{CC}=Max., V_{OUT}=GND				±1	µA
I_{OS}	Short Circuit Current[7]	V_{CC}=Max., V_{OUT}=GND		–60	–135	–240	mA
I_{OFF}	Power-Off Disable	V_{CC}=0V, V_{OUT}≤4.5V				±100	µA
I_{CC}	Quiescent Power Supply Current	V_{IN}≤0.2V, V_{IN}≥V_{CC}–0.2V	V_{CC}=Max.			+40	µA
ΔI_{CC}	Quiescent Power supply Current (TTL inputs HIGH)	V_{IN}=V_{CC}–0.6V[8]	V_{CC}=Max.			+350	µA

Electrical Characteristics For Balanced Drive Devices Over the Operating Range V_{CC}=2.7V to 3.6V

Parameter	Description	Test Conditions	Min.	Typ.[5]	Max.	Unit
I_{ODL}	Output LOW Dynamic Current[7]	V_{CC}=3.3V, V_{IN}=V_{IH} or V_{IL}, V_{OUT}=1.5V	45		180	mA
I_{ODH}	Output HIGH Dynamic Current[7]	V_{CC}=3.3V, V_{IN}=V_{IH} or V_{IL}, V_{OUT}=1.5V	–45		–180	mA
V_{OH}	Output HIGH Voltage	V_{CC}=Min., I_{OH}= –0.1 mA	V_{CC}–0.2			V
		V_{CC}=Min., I_{OH}= –8 mA	2.4[10]	3.0		V
		V_{CC}=3.0V, I_{OH}= –24 mA	2.0	3.0		V
V_{OL}	Output LOW Voltage	V_{CC}=Min., I_{OL}= 0.1mA			0.2	V
		V_{CC}=Min., I_{OL}= 24 mA		0.3	0.55	

Notes:
9. Pins with bus hold are described in Pin Description.
10. V_{OH}=V_{CC}–0.6V at rated current.

Capacitance[6] (T_A = +25˚C, f = 1.0 MHz)

Parameter	Description	Test Conditions	Typ.[5]	Max.	Unit
C_{IN}	Input Capacitance	V_{IN} = 0V	4.5	6.0	pF
C_{OUT}	Output Capacitance	V_{OUT} = 0V	5.5	8.0	pF

Power Supply Characteristics

Parameter	Description	Test Conditions		Typ.[5]	Max.	Unit
I_{CCD}	Dynamic Power Supply Current[11]	V_{CC}=Max., One Input Toggling, 50% Duty Cycle, Outputs Open, $\overline{OE}$=GND	$V_{IN}=V_{CC}$ or V_{IN}=GND	50	75	µA/MHz
I_C	Total Power Supply Current[12]	V_{CC}=Max., f_1=10 MHz, 50% Duty Cycle, Outputs Open, One Bit Toggling, $\overline{OE}$=GND	$V_{IN}=V_{CC}$ or V_{IN}=GND	0.5	0.8	mA
			$V_{IN}=V_{CC}$–0.6V or V_{IN}=GND	0.5	0.8	mA
		V_{CC}=Max., f_1=2.5 MHz, 50% Duty Cycle, Outputs Open, Sixteen Bits Toggling, $\overline{OE}$=GND	$V_{IN}=V_{CC}$ or V_{IN}=GND	2.0	3.0[13]	mA
			$V_{IN}=V_{CC}$–0.6V or V_{IN}=GND	2.0	3.3[13]	mA

Switching Characteristics Over the Operating Range V_{CC}=3.0V to 3.6V[14,15]

Parameter	Description	CY74FCT163245A CY74FCT163H245A		CY74FCT163245C CY74FCT163H245C		Unit	Fig. No.[16]
		Min.	Max.	Min.	Max.		
t_{PLH} t_{PHL}	Propagation Delay Data to Output	1.5	4.8	1.5	4.1	ns	1, 3
t_{PZH} t_{PZL}	Output Enable Time	1.5	6.2	1.5	5.8	ns	1, 7, 8
t_{PHZ} t_{PLZ}	Output Disable Time	1.5	5.6	1.5	5.2	ns	1, 7, 8
$t_{SK(O)}$	Output Skew[17]		0.5		0.5	ns	—

Notes:

11. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
12. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
    $I_C = I_{CC}+\Delta I_{CC}D_HN_T+I_{CCD}(f_0/2 + f_1N_1)$
    I_{CC} = Quiescent Current with CMOS input levels
    ΔI_{CC} = Power Supply Current for a TTL HIGH input (V_{IN}=3.4V)
    D_H = Duty Cycle for TTL inputs HIGH
    N_T = Number of TTL inputs at D_H
    I_{CCD} = Dynamic Current caused by an input transition pair (HLH or LHL)
    f_0 = Clock frequency for registered devices, otherwise zero
    f_1 = Input signal frequency
    N_1 = Number of inputs changing at f_1
    All currents are in milliamps and all frequencies are in megahertz.
13. Values for these conditions are examples of the I_{CC} formula. These limits are specified but not tested.
14. Minimum limits are specified but not tested on Propagation Delays.
15. For V_{CC} =2.7, propagation delay, output enable and output disable times should be degraded by 20%.
16. See “Parameter Measurement Information” in the General Information section.
17. Skew between any two outputs of the same package switching in the same direction. This parameter is ensured by design.

Ordering Information CY74FCT163245

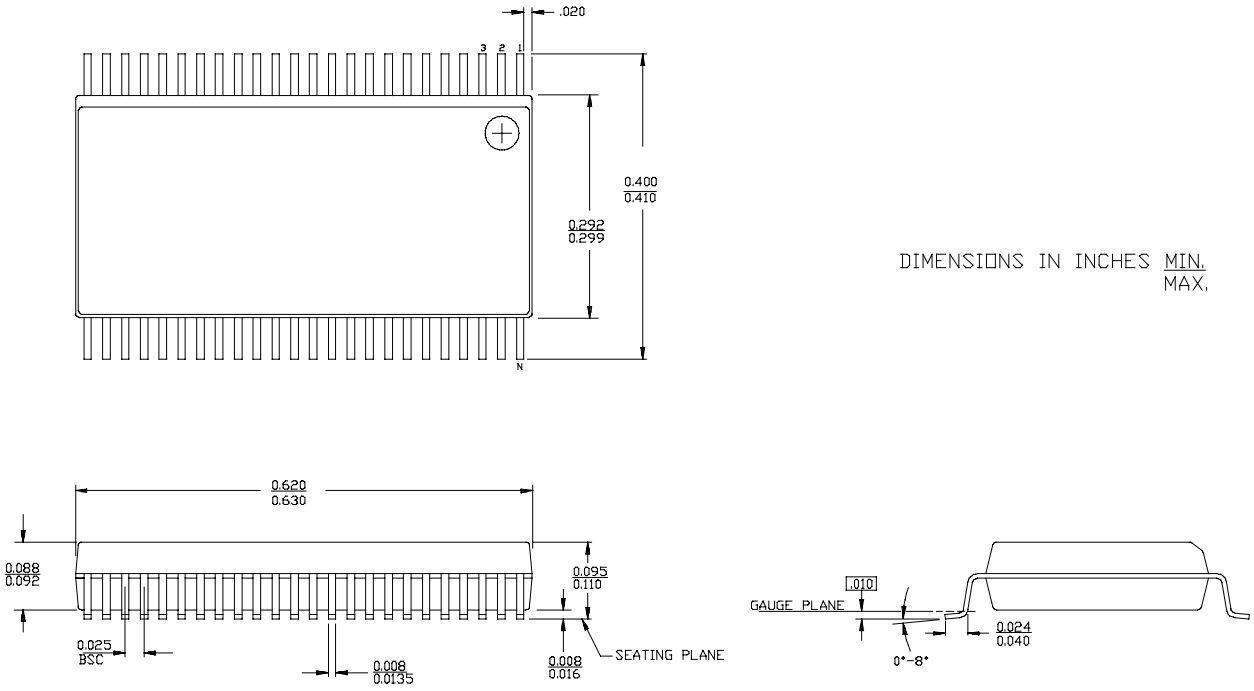
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
4.1	CY74FCT163245CPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT163245CPVC/PVCT	O48	48-Lead (300-Mil) SSOP	
4.8	CY74FCT163245APACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT163245APVC/PVCT	O48	48-Lead (300-Mil) SSOP	

Ordering Information CY74FCT163H245

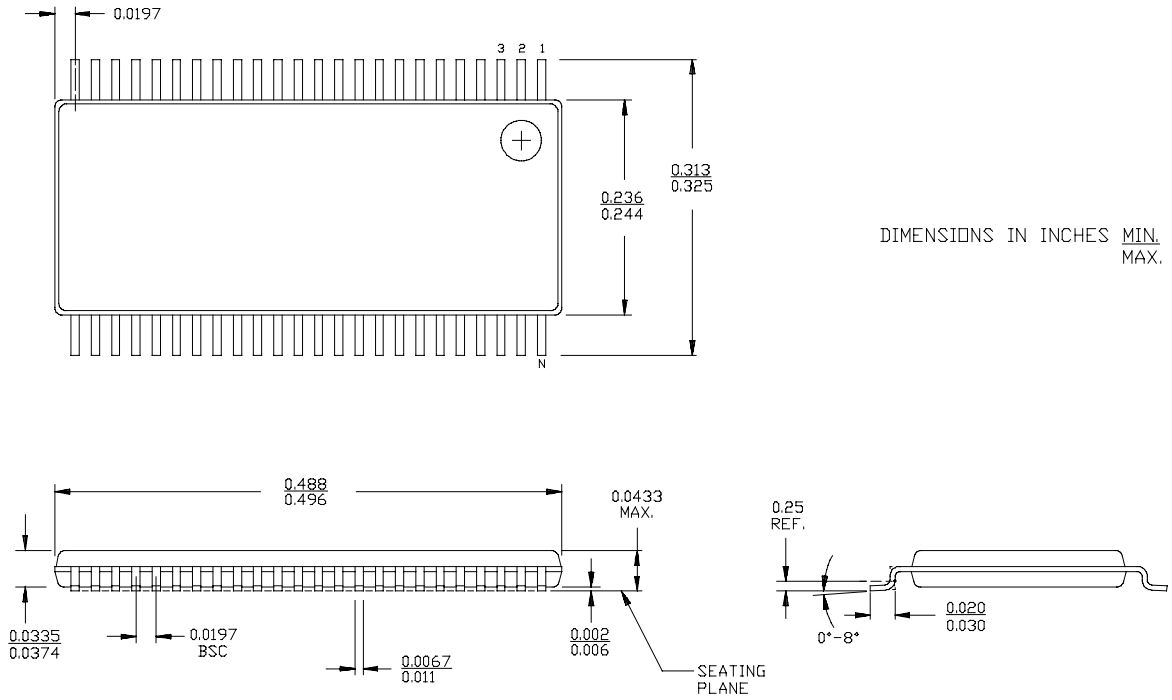
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
4.1	74FCT163H245CPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT163H245CPVC	O48	48-Lead (300-Mil) SSOP	
	74FCT163H245CPVCT	O48	48-Lead (300-Mil) SSOP	
4.8	CY74FCT163H245APVC	O48	48-Lead (300-Mil) SSOP	Industrial
	74FCT163H245APVCT	O48	48-Lead (300-Mil) SSOP	

Package Diagrams

48-Lead Shrunk Small Outline Package O48



48-Lead Thin Shrunk Small Outline Package Z48



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